

# HSF

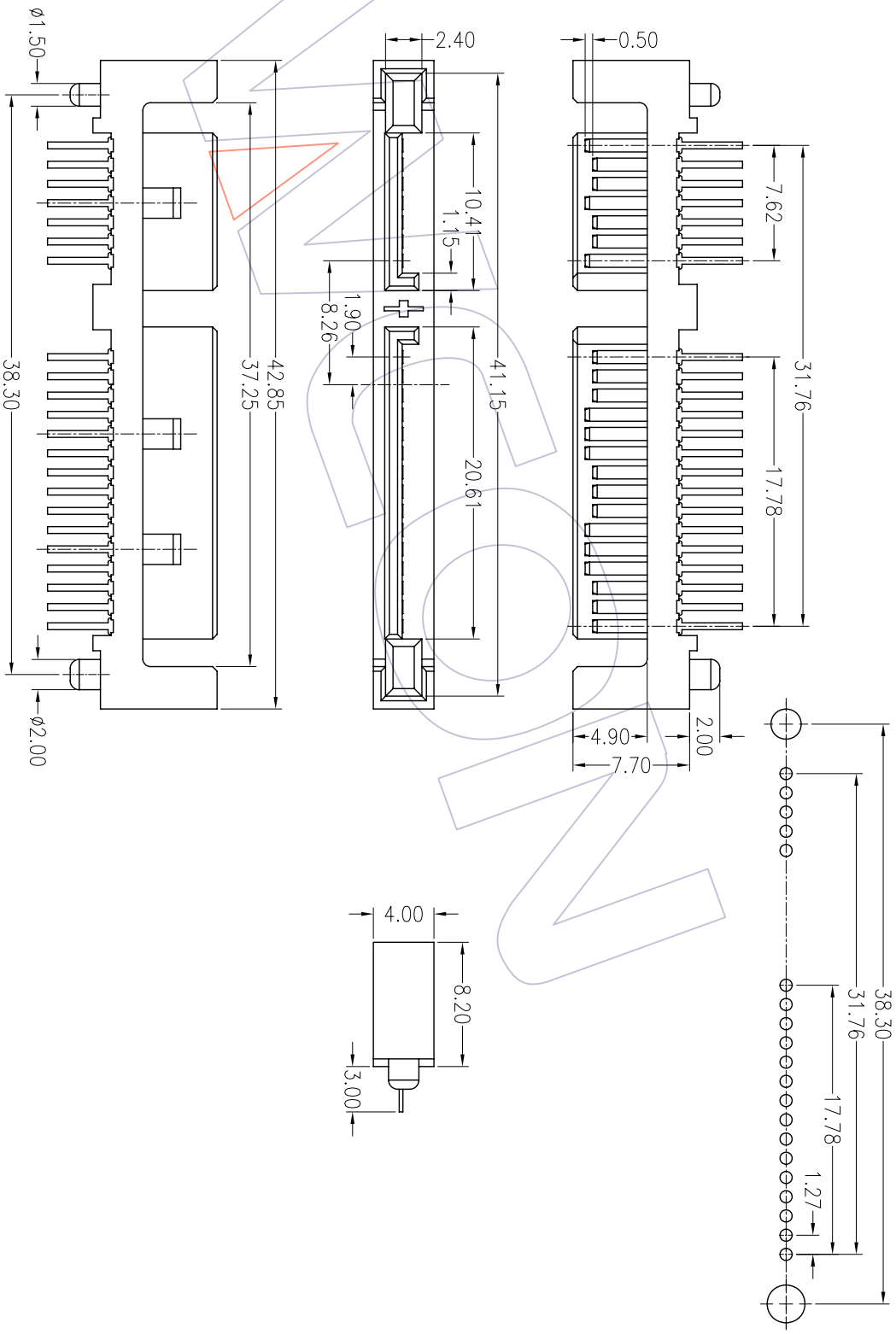
**NOTES:**

- Rated Current:1.5AMP
- Contact Resistance:30mΩ max
- Withstand Voltage:500V AC/DC
- Insulation Resistance:1000MΩ min
- Operation Temperature:-55℃ to +125℃
- Contact Material:Brass
- Contact Plating:Au or Sn Over Ni
- Insulator Material:PA6T+30%G.F UL94V-0

## Ordering Information

5411-22 D1 XX C 0 1

- Contact Plating
- G0=Gold Flash
- G1=3u"Gold
- G2=5u"Gold
- G3=10u"Gold
- G4=15u"Gold
- G5=30u"Gold
- S0=Gold Flash/Tin
- S1=3u"Gold/Tin
- S2=5u"Gold/Tin
- S3=10u"Gold/Tin
- S4=15u"Gold/Tin
- S5=30u"Gold/Tin
- SN=Tin



Recommended P.C.B Layout(Top Side)  
(PCB BOARD TOLERANCE±0.05)

|           |          |                          |  |        |   |          |  |
|-----------|----------|--------------------------|--|--------|---|----------|--|
| OPERATION |          | DRAW                     |  | SCALE  |   | PART NO. |  |
| X.X       | ±0.40    | <i>William Chen</i>      |  | 1:1    | 5411-22D1XXC01                                |          |  |
| X.XX      | ±0.25    | DESIGN                   |  | mm     | WAFER HARDWARE ELECTRONICS CO.,LTD            |          |  |
| X.XXX     | ±0.15    | CHECK                    |  | A4     | 维峰五金电子有限公司                                    |          |  |
| Angle     | ± 3'     | APPROVE                  |  | 1/1    | TITLE:  |          |  |
| DIM       | TOL      | APPROVE                  |  | PROJ.  | SATA 7P+15P MALE CONNECTOR 180° DIP WITH POST |          |  |
| REV       | DATE     | MODIFICATION DESCRIPTION |  | CHANGE | APPROVE                                       |          |  |
| A0        | 09/03/12 | NEW                      |  |        |   |          |  |

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